JFET Chopper Transistor

N–Channel – Depletion

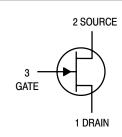
MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Drain–Gate Voltage	V _{DG}	-40	Vdc
Gate-Source Voltage	V _{GS}	-35	Vdc
Gate Current	I _G	50	mAdc
Total Device Dissipation @ T _A = 25°C Derate above 25°C	P _D	350 2.8	mW mW/°C
Lead Temperature	ΤL	300	°C
Operating and Storage Junction Temperature Range	T _J , T _{stg}	-65 to +150	°C



ON Semiconductor®

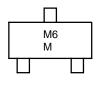
http://onsemi.com





SOT-23 **CASE 318** STYLE 10

MARKING DIAGRAM



M6 = Specific Device Code M = Date Code

ORDERING INFORMATION

Device	Package	Shipping
BSR58LT1	SOT-23	3000/Tape & Reel

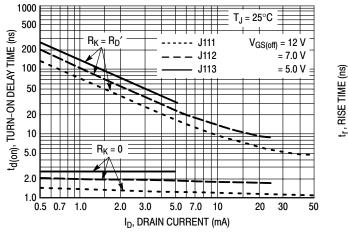
ELECTRICAL CHARACTERISTICS	S (T _A = 25°C	unless	otherwis	e noted)
Characteristic	Symbol	Min	Max	Unit

Characteristic	Symbol	Min	Max	Unit	
OFF CHARACTERISTICS					
Gate–Source Breakdown Voltage $(I_G = -1.0 \ \mu Adc)$	V _{(BR)GSS}	40	-	Vdc	
Gate Reverse Current (V _{GS} = -15 Vdc)	I _{GSS}	-	-1.0	nAdc	
Gate Source Cutoff Voltage $(V_{DS} = 5.0 \text{ Vdc}, I_D = 1.0 \mu \text{Adc})$	V _{GS(off)}	-0.8	-4.0	Vdc	
Drain–Cutoff Current (V _{DS} = 5.0 Vdc, V _{GS} = -10 Vdc)	I _{D(off)}	-	1.0	nAdc	
ON CHARACTERISTICS					

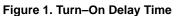
Zero–Gate–Voltage Drain Current (Note 1) (V _{DS} = 15 Vdc)	I _{DSS}	8.0	80	mAdc
Static Drain–Source On Resistance (V _{DS} = 0.1 Vdc)	r _{DS(on)}	-	60	Ω
Drain Gate and Source Gate On–Capacitance $(V_{DS} = V_{GS} = 0, f = 1.0 \text{ MHz})$	C _{dg(on)} + C _{sg(on)}	_	28	pF
Drain Gate Off–Capacitance ($V_{GS} = -10$ Vdc, f = 1.0 MHz)	C _{dg(off)}	-	5.0	pF
Source Gate Off–Capacitance (V _{GS} = –10 Vdc, f = 1.0 MHz)	C _{sg(off)}	-	5.0	pF

1. Pulse Width = $300 \mu s$, Duty Cycle = 3.0%.

BSR58LT1



TYPICAL SWITCHING CHARACTERISTICS



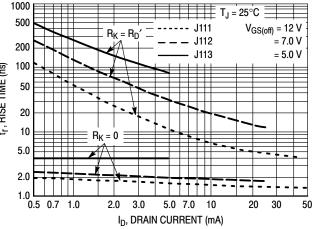


Figure 2. Rise Time

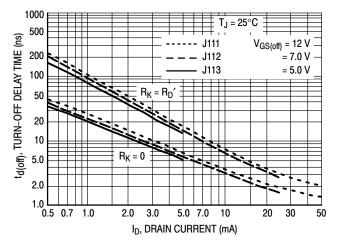


Figure 3. Turn–Off Delay Time

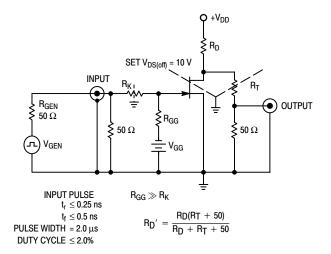


Figure 5. Switching Time Test Circuit

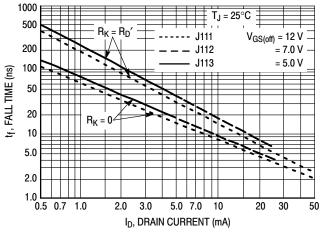


Figure 4. Fall Time

NOTE 1

The switching characteristics shown above were measured using a test circuit similar to Figure 5. At the beginning of the switching interval, the gate voltage is at Gate Supply Voltage (V_{CG}). The Drain–Source Voltage (V_{DS}) is slightly lower than Drain Supply Voltage (V_{DD}) due to the voltage divider. Thus Reverse Transfer Capacitance (C_{rss}) or Gate–Drain Capacitance (C_{gd}) is charged to $V_{GG} + V_{DS}$.

During the turn–on interval, Gate–Source Capacitance (C_{gs}) discharges through the series combination of R_{Gen} and R_K . C_{gd} must discharge to $V_{DS(on)}$ through R_G and R_K in series with the parallel combination of effective load impedance (R'_D) and Drain–Source Resistance (r_{ds}). During the turn–off, this charge flow is reversed.

Predicting turn–on time is somewhat difficult as the channel resistance r_{ds} is a function of the gate–source voltage. While C_{gs} discharges, V_{GS} approaches zero and r_{ds} decreases. Since C_{gd} discharges through r_{ds} , turn–on time is non–linear. During turn–off, the situation is reversed with r_{ds} increasing as C_{gd} charges.

The above switching curves show two impedance conditions; 1) R_K is equal to R_D , which simulates the switching behavior of cascaded stages where the driving source impedance is normally the load impedance of the previous stage, and 2) $R_K = 0$ (low impedance) the driving source impedance is that of the generator.

BSR58LT1

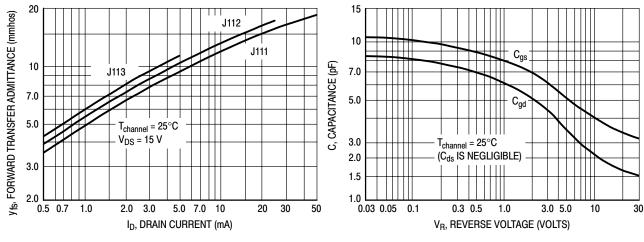


Figure 6. Typical Forward Transfer Admittance



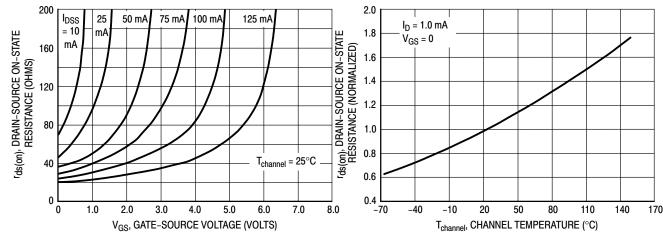


Figure 8. Effect of Gate–Source Voltage On Drain–Source Resistance

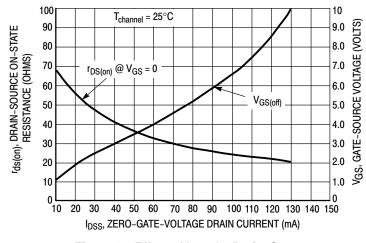


Figure 10. Effect of I_{DSS} On Drain–Source Resistance and Gate–Source Voltage

Figure 9. Effect of Temperature On Drain–Source On–State Resistance

NOTE 2

The Zero–Gate–Voltage Drain Current (I_{DSS}), is the principle determinant of other J-FET characteristics. Figure 10 shows the relationship of Gate–Source Off Voltage ($V_{GS(off)}$ and Drain–Source On Resistance ($r_{ds(on)}$) to I_{DSS}. Most of the devices will be within ±10% of the values shown in Figure 10. This data will be useful in predicting the characteristic variations for a given part number.

For example:

Unknown

 $r_{ds(on)}$ and V_{GS} range for an J112

The electrical characteristics table indicates that an J112 has an I_{DSS} range of 25 to 75 mA. Figure 10, shows $r_{ds(on)} = 52$ Ohms for I_{DSS} = 25 mA and 30 Ohms for I_{DSS} = 75 mA. The corresponding V_{GS} values are 2.2 volts and 4.8 volts.

PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-08 ISSUE AH

NOTES:

 DIMENSIONING AND TOLERANCING PER ANSI Y14.5M. 1982.

2. CONTROLLING DIMENSION: INCH. 3. MAXIMUM LEAD THICKNESS INCLUDES LEA

- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
- 4. 318-03 AND -07 OBSOLETE, NEW STANDARD 318-08.

$V \rightarrow \downarrow \qquad \qquad$	S Y

→ L ◄

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.1102	0.1197	2.80	3.04
В	0.0472	0.0551	1.20	1.40
С	0.0350	0.0440	0.89	1.11
D	0.0150	0.0200	0.37	0.50
G	0.0701	0.0807	1.78	2.04
Н	0.0005	0.0040	0.013	0.100
J	0.0034	0.0070	0.085	0.177
Κ	0.0140	0.0285	0.35	0.69
L	0.0350	0.0401	0.89	1.02
S	0.0830	0.1039	2.10	2.64
٧	0.0177	0.0236	0.45	0.60

STYLE 10: PIN 1. DRAIN 2. SOURCE 3. GATE

ON Semiconductor is a trademark and is a registered trademark of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typical" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer.

PUBLICATION ORDERING INFORMATION

Literature Fulfillment:

Literature Distribution Center for ON Semiconductor

P.O. Box 5163, Denver, Colorado 80217 USA

Phone: 303–675–2175 or 800–344–3860 Toll Free USA/Canada Fax: 303–675–2176 or 800–344–3867 Toll Free USA/Canada Email: ONlit@hibbertco.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada

JAPAN: ON Semiconductor, Japan Customer Focus Center 4–32–1 Nishi–Gotanda, Shinagawa–ku, Tokyo, Japan 141–0031 Phone: 81–3–5740–2700 Email: r14525@onsemi.com

ON Semiconductor Website: http://onsemi.com

For additional information, please contact your local Sales Representative.